

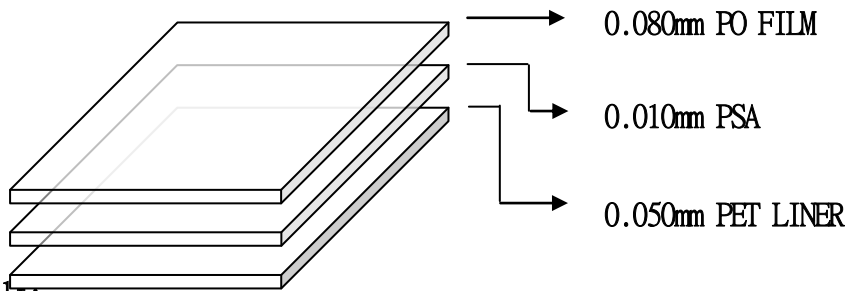
UV Tape application: Glass cutting protection, polishing, grinding, developing, cutting process, small area copper foil and PCB

UV Tape feature:

1. After UV, the viscosity is extremely low, and there is no residual glue.
2. After UV, response time is fast, effectively improving work efficiency.
3. Special viscose formula. good adhesion. will not scatter when cutting.
4. The special structure design reduces the impact on the life of the cutting knife.

REVP8530 Data Sheet

- 1、Purpose：For the analysis of physical properties, tensile strength and elongation after the product is attached to the steel plate and wafer,
- 2、Test item：Adhesion、UV de curing(500mj/cm²)、Elongation((KG/10mmW*100mm L)、Tensile strength(mm/10mmW*100mmL)
- 3、Test method：Adhesion in 1inch Width、laminare Wafer、SUS 304 after 20 minute；
Tensile strength used 1cm width and Length10cm
- 4、Structure：



5、Result:

1. REVP8530 When testing the adhesion of the steel plate and the wafer, there is no residual glue during the test. After tearing off, there is no residual glue problem, (A)

2. Product test Tensile test can find that the tensile strength is up to 0.9 (KG/10mm width * 100mm length)

Above, the elongation rate is also up to 400mm (mm/10mm width*100mm length), as shown in Table B Table A

Item	Steel		Wafer	
	Before UV (g/inch)	After UV (g/inch) (500mj/cm ²)	Before UV (g/inch)	After UV (g/inch) (500mj/cm ²)
REVP8530	996	12	755	3
	901	9	768	4
	959	13	762	4

Table B

	Elongation MD (KG/10mmW*100mmL)	Elongation TD (KG/10mmW*100mmL)	Tensile MD (mm/10mmW*100mmL)	Tensile TD (mm/10mmW*100mm L)
REVP8530	1.016	0.950	417	411